european society for precision engineering and nanotechnology Mould-integrated mechatronic fixture for error compensation in injection over-moulding of optoelectronic devices

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Development of concept

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3.

1. Initial situation and motivation



european society for precision engineering and nanotechnology 2. Claims of the research project Kinematic Requirements **Basic Concept** structure Installation space max. translatory travel: min $\pm 200 \, \mu m$ (micro-injection-tool) positioning accuracy: Х 0.1 µm max. rotatory angle: 1.8° positioning accuracy: θ_7 0.01° LED 20 in the second plastics optics 70 leadframe euspen 🜌 Fraunhofer Advance the arts, sciences and technology of precision engineering, micro-engineering and nanotechnology

3. Development of concept

IWU





 $[10^{-7}m]$

lever type 80

maximum stress

[N/mm²]

movable bridge

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■ fixed bridge

stiffness [10⁻²N/µm]

IWU

110





IWU

european society for precision engineering and nanotechnology **3. Development of concept Kinematic** Requirements **Basic Concept** structure Synthesis and optimization of compliant mechanism Gesamtverformung Typ: Gesamtverformung Einheit: mm 0.6564 Max 0.5834 0,5105 h_{1} 0.4376 0,3647 0,2917 u 0,2188 0,1459 0,07293 0 Min 20.000 (mm Vergleichsspannung ΔI Typ: Vergleichsspannung (von Mises) Einheit: MPa ΔI 218 187 156 93,6 62,4 piezo actuator 31,2 0.0202 Min 1_{PA} $\mathsf{F}_{\mathsf{Block}}$ 111 euspen 🜌 Fraunhofer Advance the arts, sciences and technology of precision engineering, micro-engineering and nanotechnology



european society for precision engineering and nanotechnology **3. Development of concept** Mould-Kinematic **Basic Concept integration** structure additional ejector Upper Part pin in cavity plate Cavity compression spring Core additional Plate compliant mechanism for Z-translation Lower Part conventional ejector pin in mould euspen 🜌 Fraunhofer Advance the arts, sciences and technology of precision engineering, micro-engineering and nanotechnology

3. Development of concept

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Basic Concept

Kinematic structure

Mouldintegration

Design of concept

- 3 capacitive sensors on cavity plate
- 1 absolute system in upper part
- Alignment of the device in the mould by 8 fine adjustment screws

Modular mould concept

Injection moulding tool with standard components:

- ✓ Plates and risers
- ✓ Guidance and Ejector system
- ✓ Fasteners



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4. Motion and thermal analysis



Results of FE-Simulation

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Motion	Value
Travel X	±350 μm
Travel Y	±310 μm
Angle O _z	±1,88°
parasitic motion in X-axis	0,02 µm / 0,0004°
parasitic motion in Y-axis	0,08 µm / 0,007°

Temperature dependency:

Maximum travel depends on the temperature

- \rightarrow If temperature increases, maximum travel decreases by about 0,5 μ m/K
- ightarrow Constant temperature during operation is assumed

5. Conclusion and Outlook

Design of concept

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- Compliant mechanisms allow high-precision positioning
- Parameter optimisation increases deflections and reduce parasitic movements
- Highly compact systems can be integrated into an injection moulding tool

Outlook



Realisation of the actuator system, commissioning and measurements of the adjustment ranges during operation **Benefits**

Active error compensation inside the mould

Additional assembly steps are not necessary

Production of the electronic components can become more cost-effective





